



SOT1089

plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

9 January 2017

Package information

1. Package summary

Dimensions (mm)	1.35 x 1 x 0.5
Terminal position code	D (double)
Package type descriptive code	XSON8
Package outline version code	SOT1089
Manufacturer package code	SOT1089
Package type industry code	XSON8
Package outline version description	plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package body material type	P
JEDEC package outline code	MO-252
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	IC26_CHAPTER_6_2000
Mounting method type	S (surface mount)
Package life cycle status	REL
Major version date	18-11-2009
Minor version date	10-5-2012
Security status	COMPANY PUBLIC
Modified date	10-5-2012
Issue date	12-4-2010
Web publication date	28-11-2012
Initial web publication date	9-3-2011
Customer specific indicator	N
Maturity	Product
Package author	Nair Deepa
Package approver	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	-	-	-	0.5	mm
D	package length	1.3	-	1.35	1.4	mm
E	package width	0.95	-	1	1.05	mm
e	nominal pitch	-	-	0.55	-	mm



plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

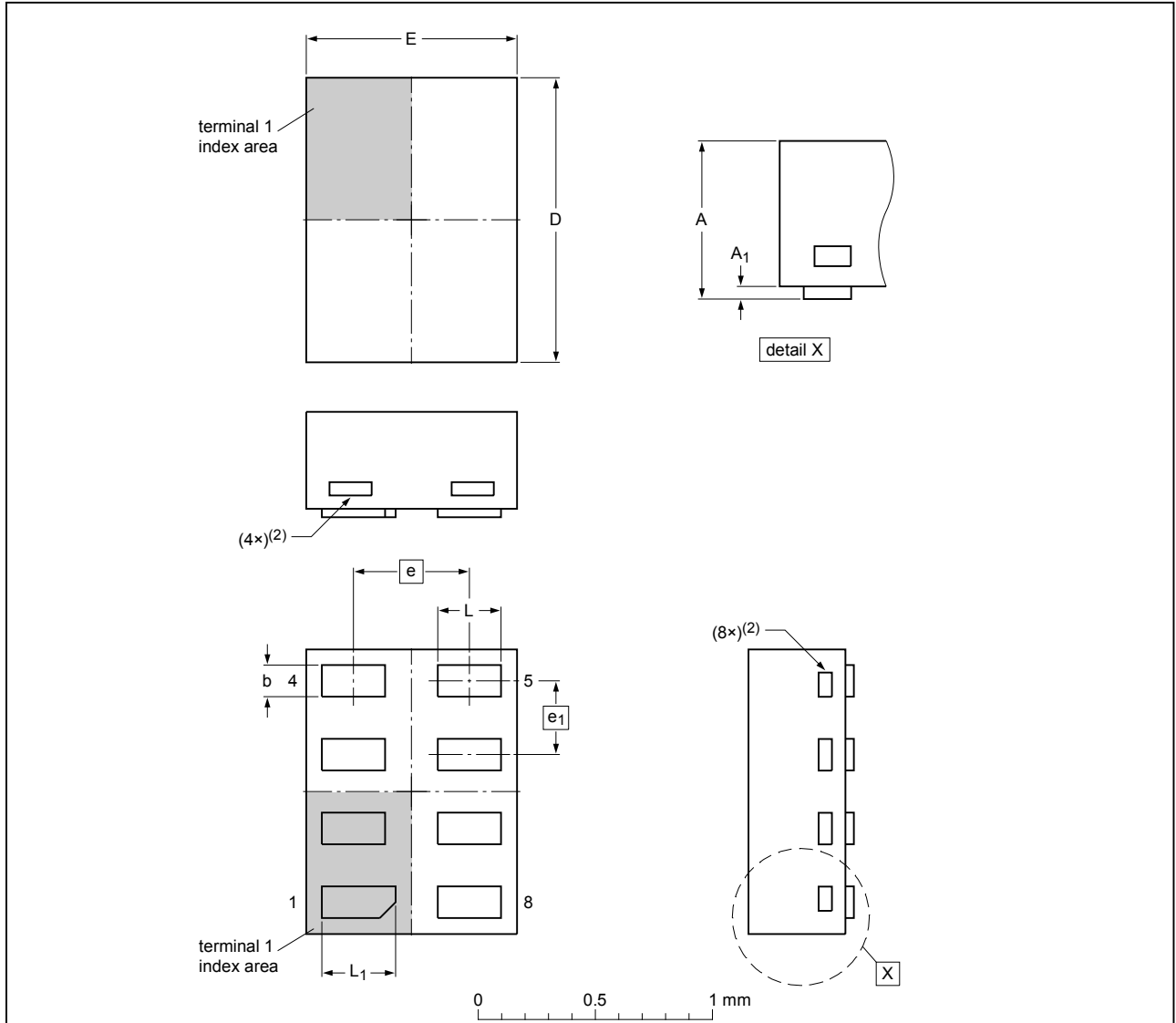
Symbol	Parameter		Min	Typ	Nom	Max	Unit
n ₂	actual quantity of termination		-	-	8	-	

plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

2. Package outline

XSON8: extremely thin small outline package; no leads; 8 terminals; body 1.35 x 1 x 0.5 mm

SOT1089



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
mm	max 0.5	0.04	0.20	1.40	1.05			0.35	0.40
	nom 0.15	1.35	1.00	0.55	0.35	0.30	0.35		
	min 0.12	1.30	0.95					0.27	0.32

Note

- Including plating thickness.
- Visible depending upon used manufacturing technology.

sot1089_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1089		MO-252			10-04-09 10-04-12

Fig. 1. Package outline XSON8 (SOT1089)

plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

3. Soldering

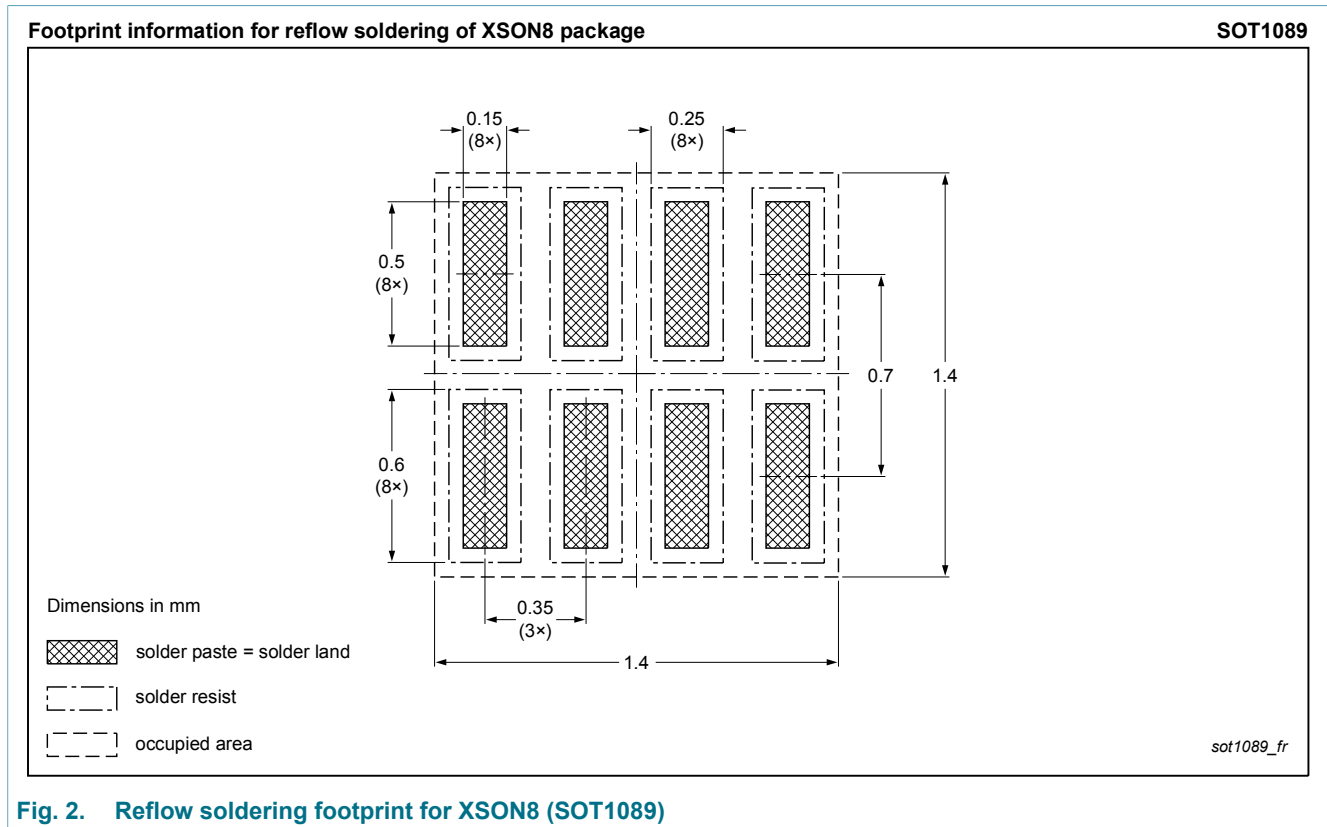


Fig. 2. Reflow soldering footprint for XSON8 (SOT1089)

plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

4. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

5. Contents

1. Package summary.....	1
2. Package outline.....	3
3. Soldering.....	4
4. Legal information.....	5

© NXP Semiconductors N.V. 2017. All rights reserved

For more information, please visit: <http://www.nxp.com>
For sales office addresses, please send an email to: salesaddresses@nxp.com
Date of release: 9 January 2017
